



Glass Passivated Bridge Rectifiers

Features

- Glass passivated chip
- Low forward voltage drop
- Ideal for printed circuit board
- High surge current capability
- Meet UL flammability classification 94V-0

Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any

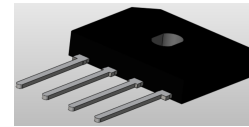
Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

Applications

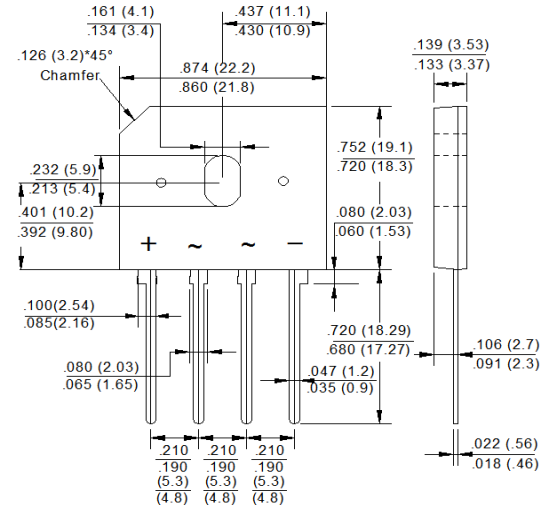
- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.

Reverse Voltage - 50 to 1000 Volts
Forward Current - 25 Amperes

GBU



RoHS
COMPLIANT



Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristics	Symbol	GBU	GBU	GBU	GBU	GBU	GBU	GBU	Unit
		25005	2501	2502	2504	2506	2508	2510	
Maximum Repetitive Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	v
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	v
Maximum Average Forward (with heatsink Note 2)	I(AV)	25.0							A
Rectified Current @ Tc=100℃ (without heatsink)		4.2							
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	IFSM	350							A
I²t Rating for Fusing (t<8.3mS)	I²t	508							A²s
Peak Forward Voltage per Diode at 12.5A DC	VF	1.0							V
Maximum DC Reverse Current at Rated @Tj=25℃	IR	5.0							µA
DC Blocking Voltage per Diode @Tj=125℃		500							
Typical Junction Capacitance per Diode (Note1)	CJ	70							pF
Typical Thermal Resistance to Ambient (Note2)	RθJA	10							℃/W
Typical Thermal Resistance to case (Note2)	RθJC	2							
Typical Thermal Resistance to lead (Note2)	RθJL	2.2							
Operating Junction Temperature Range	TJ	-55 to +150							℃
Storage Temperature Range	TSTG	-55 to +150							℃

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

2. Device mounted on 100mm*100mm*1.6mm Cu plate heatsink.

3. The typical data above is for reference only



Fig. 1 - Forward Current Derating Curve

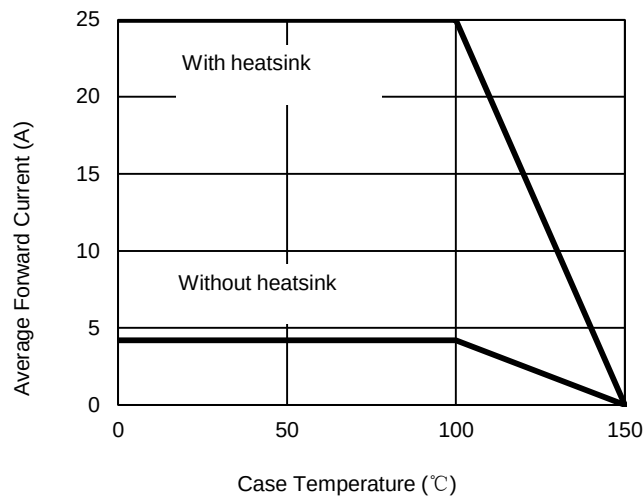


Fig. 2 - Maximum Non-Repetitive Surge Current

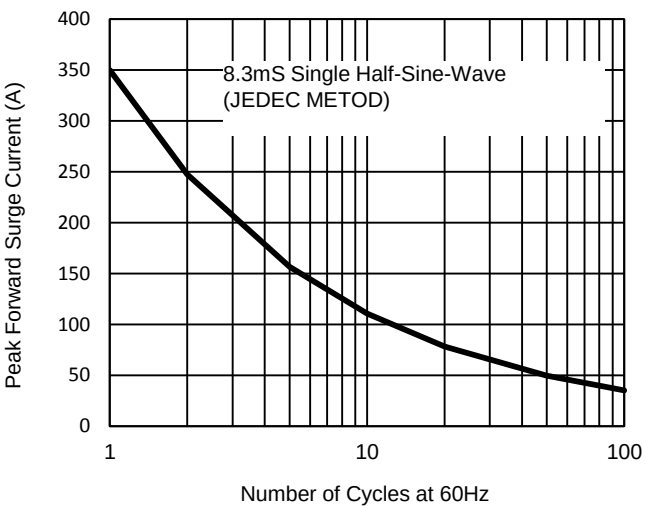


Fig. 3 - Typical Reverse Characteristics

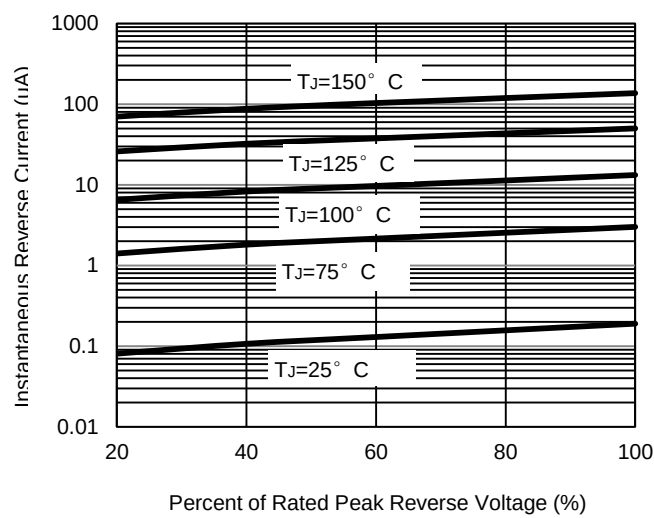
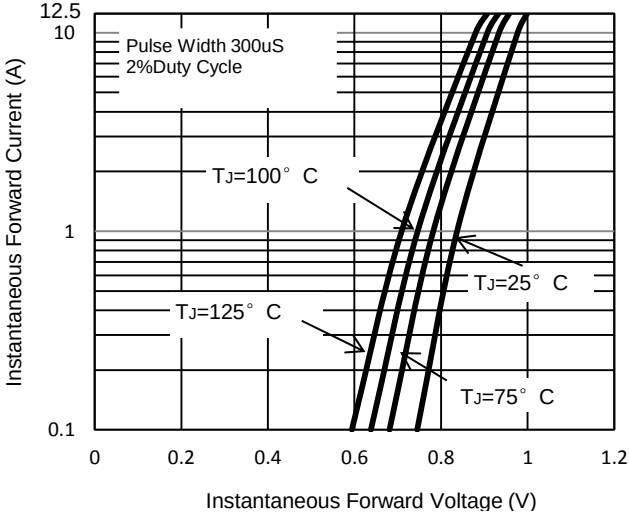


Fig. 4 - Typical Forward Characteristics





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